

### Purpose

This declaration is intended to disclose substances contained in THAT 2181S-T series integrated circuits. The table below lists Materials and Substances included in the Joint Industry Guide (JIG) - Material Composition Declaration Guide, released on September 19, 2003. This covers all materials defined in Article 4.1 of the European Directive 2002/95/EC on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Directive).

### Materials Declaration

Leadframe Plating: 100% Tin (Sn)				Percent by weight of homogenous material <sup>1</sup>				
Controlled Chemicals		Threshold Limits		IC itself	Shipping Container			
		RoHS	JIG		Box	Bag	Tube	End Plugs
Cadmium	Elemental	0.01%	0.0075%, and not intentionally added	ND	ND <sup>2</sup>	ND	ND	ND
	Cd Compounds			ND	ND	ND	ND	ND
Lead	Elemental	0.10%	0.10%, and not intentionally added	ND	ND	ND	ND	ND
	Pb Compounds			0.014%	ND	ND	ND	ND
Mercury	Elemental	0.10%	0.10%, and not intentionally added	ND	ND	ND	ND	ND
	Hg Compounds			ND	ND	ND	ND	ND
Hexavalent Chromium	Elemental	0.10%	0.10%, and not intentionally added	ND	ND	ND	ND	ND
	Cr <sub>6</sub> Compounds			ND	ND	ND	ND	ND
Polybrominated biphenyls (PBB)				ND	ND	ND	ND	ND
Polybrominated diphenylethers (PBDE)				ND	ND	ND	ND	ND
Polychlorinated biphenyls (PCB)				ND	ND	ND	ND	ND
Polychlorinated naphthalenes (PCN)				ND	ND	ND	ND	ND
Polychlorinated terphenyls (PCT)				ND	ND	ND	ND	ND
Chlorinated parafins (CP)		Not Regulated	Not intentionally added	ND	ND	ND	ND	ND
Other Chlorinated Compounds				ND	ND	ND	ND	ND
Azo Compounds				ND	ND	ND	ND	ND
Tributyltin compounds				ND	ND	ND	ND	ND
Triphenyltin compounds				ND	ND	ND	ND	ND
Other brominated organic compounds		Not Regulated	0.01%	ND	ND	ND	ND	ND
Antimony				1.8%	ND	ND	ND	ND
Other antimony compounds				ND	ND	ND	ND	ND
Asbestos				ND	ND	ND	ND	ND
Polyvinyl chloride (PVC) and blends				ND	ND	ND	<0.001% of Vinyl Chloride	

### Notes

1. A material is homogeneous if its compound concentration (as % wt) is not changed by mechanical disjoining (cutting, grinding, etc.). For example, in an integrated circuit, the homogenous materials would be the ink, mold compound, gold wires, die, die attach epoxy, base lead frame material and lead frame surface finish
2. ND - None Detected.

### Disclaimer

This information has been collected from THAT Corporation's manufacturing facilities and our worldwide supply chain. To the best of our knowledge, it is correct as of the date indicated on this page. However, we cannot guarantee its completeness or accuracy as some information has been derived from data sources outside the company.